ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES®	ckburn, Illinois. A	Il rights reserved un ntions.	ider both	This docume evel parts, t	ent is a declaration	ion of the s encompasse	ubstance es all low	s within the manufactu er level materials for v	arer listed which the	item. Note: if nanufacturer	the item is an as has engineering	ssembly with lower responsibility.	
2-21.1 IPC Web Site for Information on IPC-1752 Standard Form Type Distribute					Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information													
Company name* Company unique ID					Unique ID Authority				Respon	Response Date*			
onsemi					2024-05					4-05-20			
ntact Name Title - Contact				1	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative]	Phone - Representative* En				Email -	Email - Representative*			
Product-Env-Stewards Product Enviro Compliance					NA Product-Env-Stewards@onsemi.com					om			
Requester Item Number Mfr	Requester Item Number Mfr Item Number Mfr Item				Effective Date	Version		Manufacturing Site		Weight*	UOM	Unit Type	
R391	0-CFAB-E1T Preconfig DSP: Rhythm 250/Reel		ythm Tape & Ro	eel	2024-05-20					60.89737	mg	Each	
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSI					Peak Pro	ess Body T	emperat	ure Max Time at Peal	k Tempera	ture Numbe	er of Reflow Cy	cles	
SnAgCuCU Alloy3260C30seconds3								nds 3					
Comments													
ATTENTION: MSL 3 Rated item requires Bake an	d Dry Pack (afte	electrical test)											
For more information regarding material composit	on please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7c-I Electrical and electronic c	omponents containing lead in a glass o	r ceramic other than dielectric ceramic	in capacitors,	e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to ha			ice drop-dowi	n. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature R	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Capacitor	0.9	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.147	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.0058	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0232	mg
			Supplier	Misc.	Proprietary Data		0.049	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		0.294	mg
			В	Nickel (Ni)	7440-02-0		0.05	mg
			Supplier	Copper (Cu)	7440-50-8		0.261	mg
vie	4.889605	mg	Supplier	Silicon (Si)	7440-21-3		4.8896	mg
Laminate Board	36.830296	mg		Defoamers	n/a		0.0006	mg
			Supplier	Phthalocyanine blue	N/A		0.0123	mg
			Supplier	Organic Filler	N/A		0.0123	mg
			Supplier	Acrylate resin	N/A		0.8572	mg
			Supplier	Diproplyeneglycolmonomethylether	34590-97-8		0.0019	mg
			Supplier	Cured Thermosetting Resin	Proprietary Data		5.6678	mg
			Supplier	Silica	Proprietary Data		0.0001	mg
			Supplier	Talc	14807-96-6		0.0612	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		0.0037	mg
			Supplier	Naphthalene	91-20-3		0.0003	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		5.6678	mg
			Supplier	Photoinitiator	Proprietary Data		0.0006	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0005	mg
			В	Nickel (Ni)	7440-02-0		0.0009	mg
			Supplier	Gold (Au)	7440-57-5		0.0004	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		0.0006	mg
			Supplier	Copper (Cu)	7440-50-8		23.8076	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.7347	mg
Mold Compound-Black	14.5	mg		Epoxy resin	proprietary data		1.16	mg
			Supplier	Phenol Resin	Proprietary Data		0.725	mg
			Supplier	Metal Hydroxide	Proprietary Data		0.145	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.625	mg
			Supplier	Carbon Black (C)	1333-86-4		0.145	mg

			Supplier	Fused Silica (SiO2)	60676-86-0		8.7	mg
Resistor 0.	0.04067	mg	Supplier	C.I. Pigment Black	68186-91-4		0.0005	mg
			Supplier	Epoxy Resin	25068-38-6		0.0003	mg
			Supplier	Glass Frit	65997-18-4	7c	0	mg
			Supplier	Boron (B)	7440-42-8		0	mg
			Supplier	Silver (Ag)	7440-22-4		0.0014	mg
			Supplier	Tin (Sn)	7440-31-5		0.0027	mg
			В	Bismuth Trioxide (Bi2O3)	1304-76-3		0.0003	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0006	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0006	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0284	mg
			Supplier	Ruthenium Oxide (RuO2)	12036-10-1		0.0004	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0	mg
			В	Nickel (Ni)	7440-02-0		0.0052	mg
Solder Paste	3.089286	mg	Supplier	2-(2-Hexyloxyethoxy) ethanol	112-59-4		0.1236	mg
			Supplier	Denatured Acid Hydrogenation Rosin	Proprietary		0.1236	mg
			Supplier	Dimer Acid	Proprietary		0.0618	mg
			Supplier	Silver (Ag)	7440-22-4		0.0927	mg
			Supplier	Tin (Sn)	7440-31-5		2.6568	mg
			Supplier	Copper (Cu)	7440-50-8		0.0309	mg
Wire Bond - Au	0.647515	mg	Supplier	Gold (Au)	7440-57-5		0.6475	mg